



P-Channel Enhancement-Mode MOSFET (-20V, -4.9A)

PRODUCT SUMMARY

V_{DSS}	I_D	$R_{DS(on)}$ (m Ω) Typ.
-20V	-4.9A	34 @ $V_{GS} = -4.5V, I_D = -4.5A$
		44 @ $V_{GS} = -2.5V, I_D = -2.5A$

Features

- Super high dense cell trench design for low $R_{DS(on)}$
- Rugged and reliable
- SOT-23 package
- Lead (Pb) -free and halogen-free

	<p>EN2305 Pin Assignment & Symbol 3-Lead Plastic SOT-23 Pin 1: Gate Pin 2: Source Pin3: Drain</p>	
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Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current (Continuous)	-4.9	A
I_{DM}	Drain Current (Pulsed) ^a	-15	A
P_D	Total Power Dissipation @ $T_A = 25^\circ\text{C}$	1.7	W
I_S	Maximum Diode Forward Current	-4.9	A
T_J, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
R_{QJA}	Thermal Resistance Junction to Ambient (PCB mounted) ^b	75	$^\circ\text{C/W}$

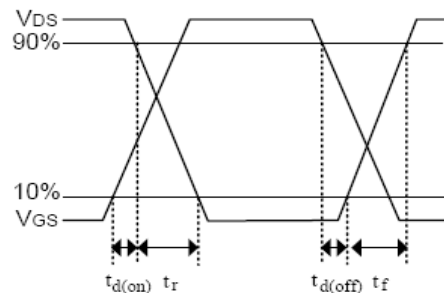
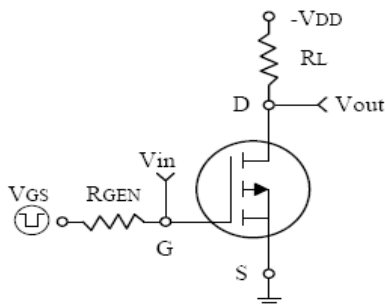
a: Repetitive Rating; Pulse width limited by the maximum junction temperature.

b: 1-in² 2oz Cu PCB board

Electrical Characteristics ($T_A=25^\circ\text{C}$, unless otherwise noted)

Symbol	Characteristic	Test Conditions	Min.	Typ.	Max.	Unit
• Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20V, V_{GS}=0V$	-	-	1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA
• On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.45		-1	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=-4.5V, I_D=-4.9A$	-	34	45	m Ω
		$V_{GS}=-2.5V, I_D=-3A$		44	60	
• Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1\text{MHz}$	-	740	-	PF
C_{oss}	Output Capacitance		-	290	-	
C_{rss}	Reverse Transfer Capacitance		-	190	-	
• Switching Characteristics						
Q_g	Total Gate Charge	$V_{DS}=-10V, I_D=-1A, V_{GS}=-4.5V$	-	7.8	-	nC
Q_{gs}	Gate-Source Charge		-	1.2	-	
Q_{gd}	Gate-Drain Charge		-	1.6	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=-4V, R_L=1.2\Omega, I_D=1A, V_{GEN}=-4.5V, R_G=1\Omega$	-	12	-	nS
t_r	Turn-on Rise Time		-	35	-	
$t_{d(off)}$	Turn-off Delay Time		-	30	-	
t_f	Turn-off Fall Time		-	10	-	
• Drain-Source Diode Characteristics						
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS}=0V, I_S=-1A$	-	-	-1.2	V

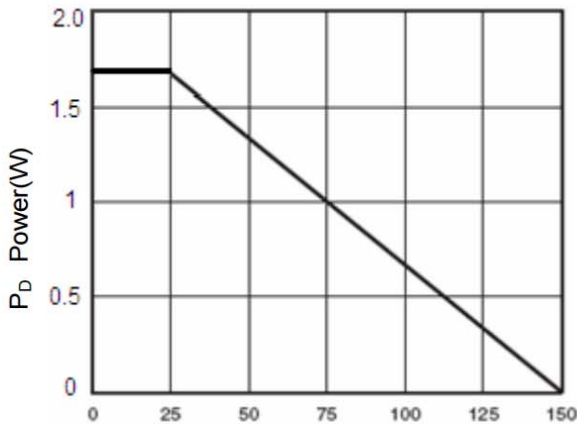
Note: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$



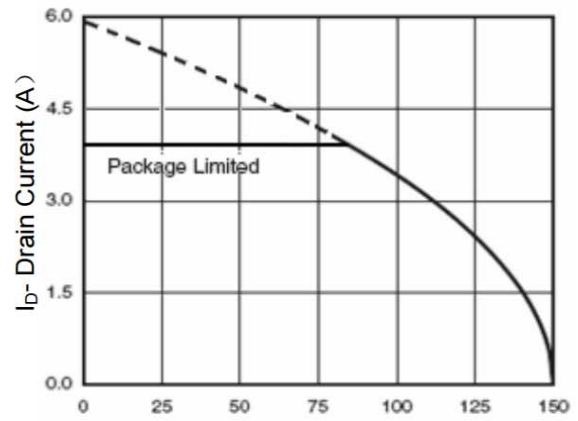
Switching Test Circuit and Switching Waveforms



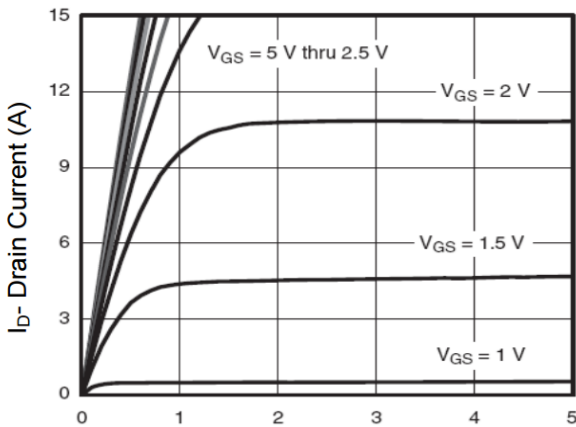
Typical Characteristics Curves (Ta=25°C, unless otherwise note)



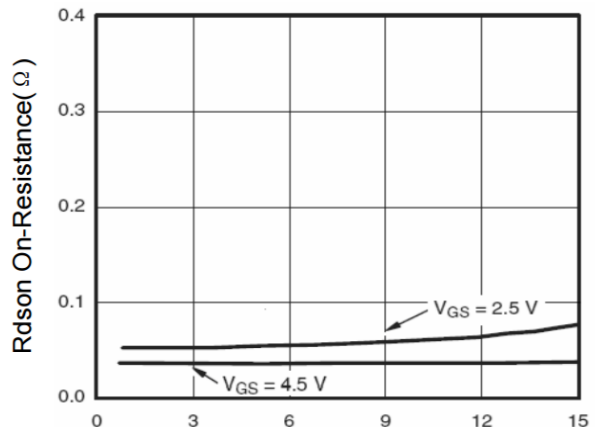
T_J-Junction Temperature(°C)
Figure 1 Power Dissipation



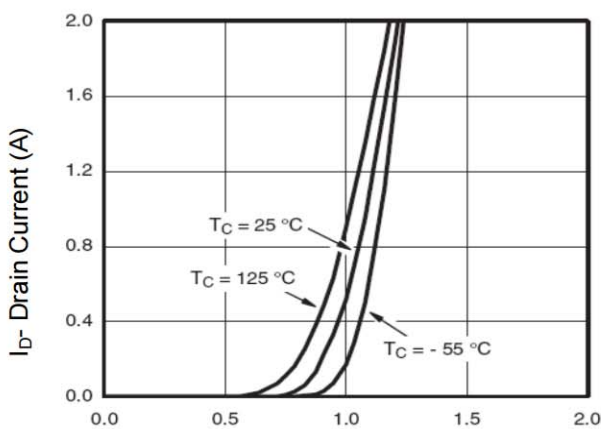
T_J-Junction Temperature(°C)
Figure 2 Drain Current



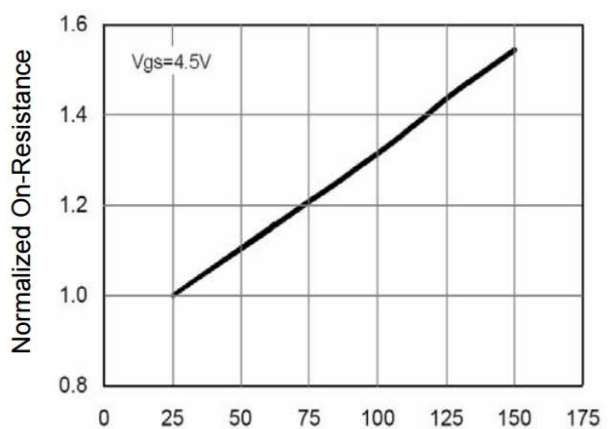
V_{ds} Drain-Source Voltage (V)
Figure 3 Output Characteristics



I_D- Drain Current (A)
Figure 4 Drain-Source On-Resistance



V_{gs} Gate-Source Voltage (V)
Figure 5 Transfer Characteristics



T_J-Junction Temperature(°C)
Figure 6 Drain-Source On-Resistance

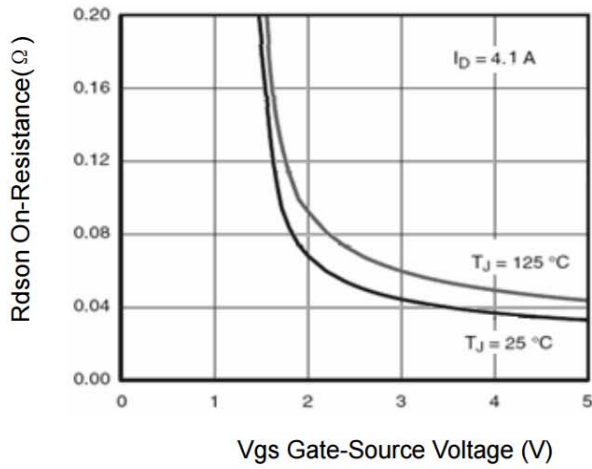


Figure 7 Rdson vs Vgs

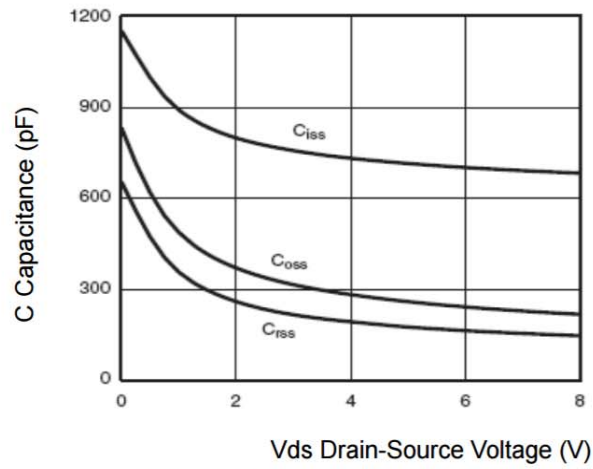


Figure 8 Capacitance vs Vds

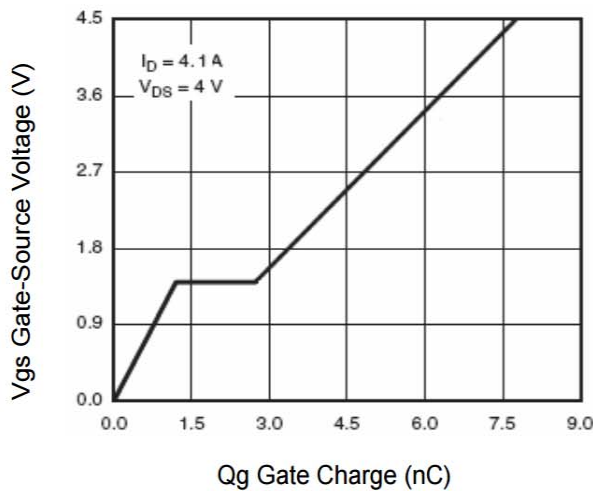


Figure 9 Gate Charge

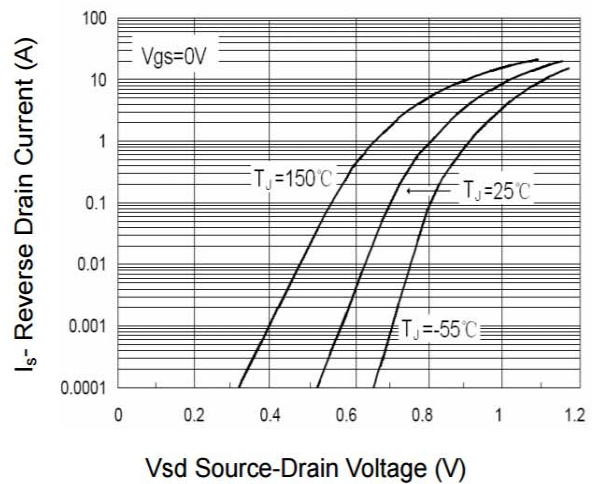


Figure 10 Source- Drain Diode Forward

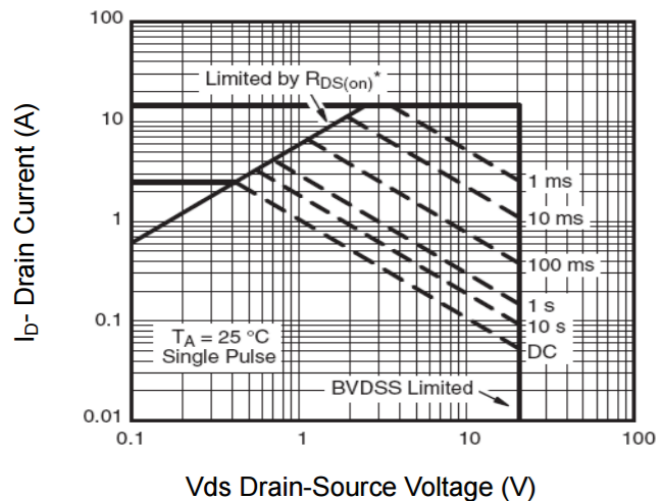


Figure 11 Safe Operation Area

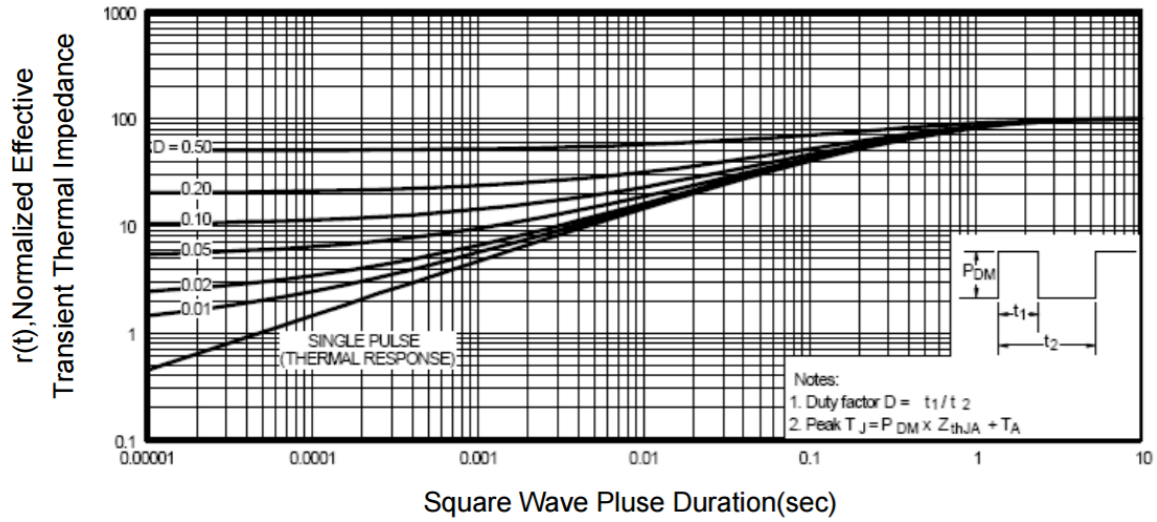
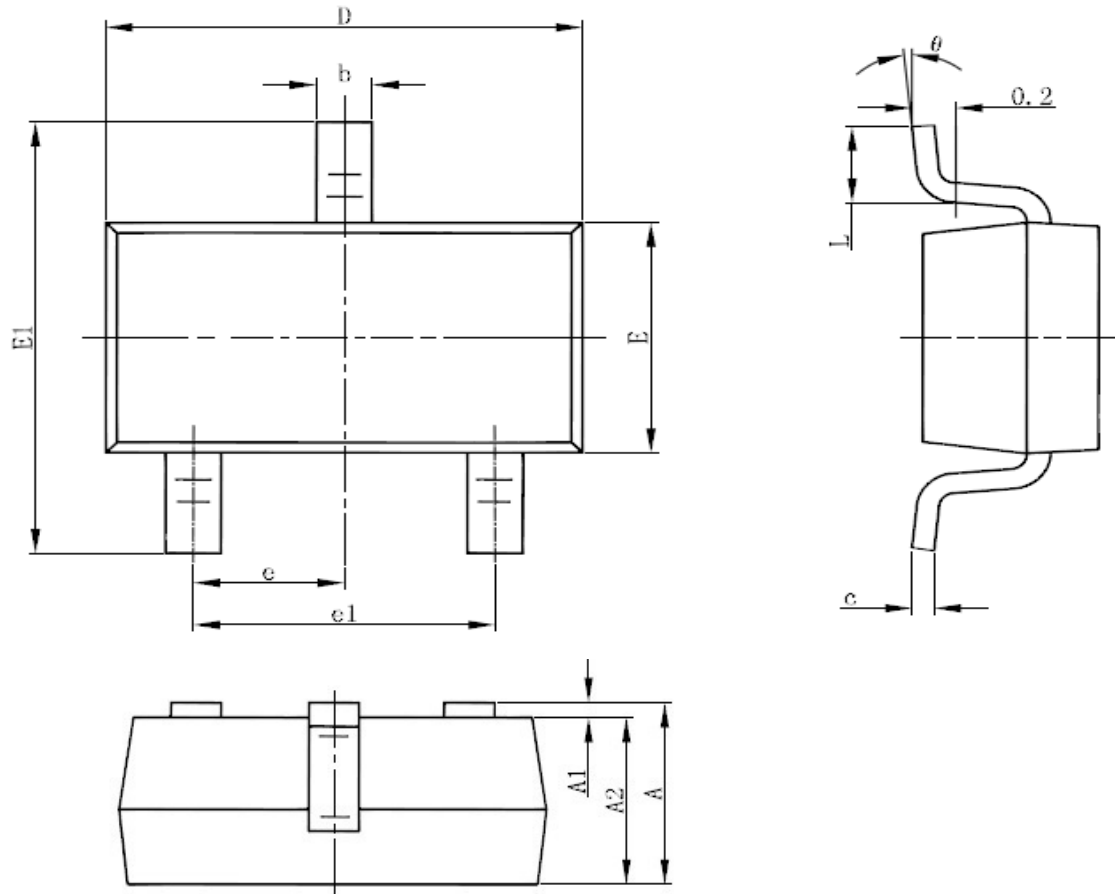


Figure 12 Normalized Maximum Transient Thermal Impedance

SOT-23 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°